

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0	0.66	0.07
	Doped silicon	Silicon (Si)	7440-21-3	0.49	99.34	9.93
		Subtotal		0.49	100	10
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03	10.0	0.71
	Silver alloy	Silver (Ag)	7440-22-4	0.01	2.0	0.14
	Lead alloy	Lead (Pb)	7439-92-1	0.31	88.0	6.25
		Subtotal		0.35	100	7.1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.2	100.0	4.08
		Subtotal		0.2	100	4.08
Lead Frame	Iron-nickel alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.41
	Iron-nickel alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.73	1.08	14.86
	Iron-nickel alloy	Copper (Cu)	7440-50-8	66.67	98.79	1359.35
		Subtotal		67.42	99.9	1374.62
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.01	100.0	20.68
		Subtotal		1.01	100	20.68
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.37	4.5	27.95
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.05	10.0	62.1
	Filler	Silica fused	60676-86-0	22.84	75.0	465.75
	Metal hydroxide	Metal hydroxide		3.05	10.0	62.1
	Carbon Black	Carbon black	1333-86-4	0.15	0.5	3.1
		Subtotal		30.46	100	621
		Total		99.93	100	2037.48

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